

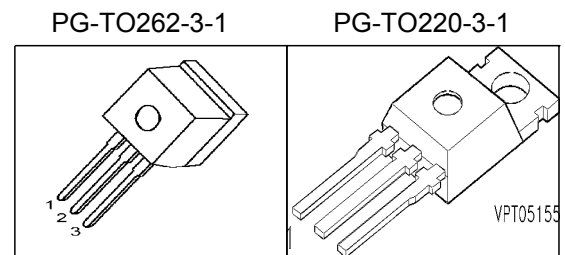
SIPMOS® Power-Transistor

Feature

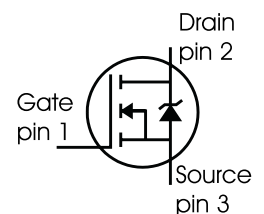
- N-Channel
- Enhancement mode
- 175°C operating temperature
- Avalanche rated
- dv/dt rated
- Pb-free lead plating; RoHS compliant

Product Summary

V_{DS}	100	V
$R_{DS(on)}$	44	mΩ
I_D	35	A



Type	Package	Ordering Code	Marking
SPP35N10	PG-TO220-3-1	Q67042-S4123	35N10
SPI35N10	PG-TO262-3-1	Q67042-S4124	35N10



Maximum Ratings, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current	I_D		A
$T_C=25\text{ °C}$		35	
$T_C=100\text{ °C}$		26.4	
Pulsed drain current	$I_D \text{ puls}$	140	
$T_C=25\text{ °C}$			
Avalanche energy, single pulse	E_{AS}	245	mJ
$I_D=35\text{ A}$, $V_{DD}=25\text{ V}$, $R_{GS}=25\text{ Ω}$			
Reverse diode dv/dt	dv/dt	6	kV/μs
$I_S=35\text{ A}$, $V_{DS}=80\text{ V}$, $di/dt=200\text{ A/μs}$, $T_{jmax}=175\text{ °C}$			
Gate source voltage	V_{GS}	±20	V
Power dissipation	P_{tot}	150	W
$T_C=25\text{ °C}$			
Operating and storage temperature	T_j, T_{stg}	-55... +175	°C
IEC climatic category; DIN IEC 68-1		55/175/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	-	1	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	62	
SMD version, device on PCB: @ min. footprint @ 6 cm ² cooling area ^{F)}	R_{thJA}	-	-	62 40	

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage $V_{GS}=0V, I_D=1mA$	$V_{(BR)DSS}$	100	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=83\mu A$	$V_{GS(th)}$	2.1	3	4	
Zero gate voltage drain current $V_{DS}=100V, V_{GS}=0V, T_j=25^\circ C$ $V_{DS}=100V, V_{GS}=0V, T_j=125^\circ C$	I_{DSS}	-	0.01 1	1 100	μA
Gate-source leakage current $V_{GS}=20V, V_{DS}=0V$	I_{GSS}	-	1	100	
Drain-source on-state resistance $V_{GS}=10V, I_D=26.4A$	$R_{DS(on)}$	-	36	44	$m\Omega$

¹Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic Characteristics

Transconductance	g_{fs}	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ $I_D = 26.4\text{A}$	12	23	-	S
Input capacitance	C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	-	1180	1570	pF
Output capacitance	C_{oss}		-	245	326	
Reverse transfer capacitance	C_{rss}		-	137	206	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 50\text{V}$, $V_{GS} = 10\text{V}$, $I_D = 35\text{A}$, $R_G = 7\Omega$	-	12.2	18.3	ns
Rise time	t_r		-	63	95	
Turn-off delay time	$t_{d(off)}$		-	39	59	
Fall time	t_f		-	23	34	

Gate Charge Characteristics

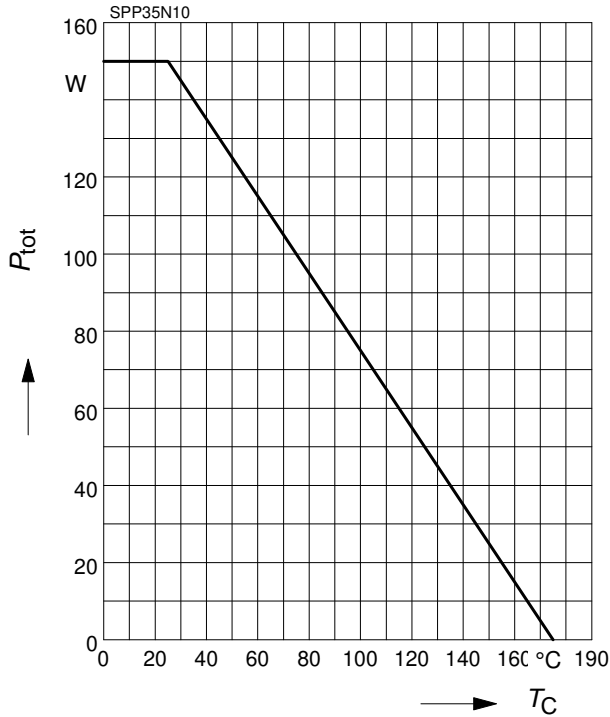
Gate to source charge	Q_{gs}	$V_{DD} = 80\text{V}$, $I_D = 35\text{A}$	-	6.5	8.6	nC
Gate to drain charge	Q_{gd}		-	27	41	
Gate charge total	Q_g	$V_{DD} = 80\text{V}$, $I_D = 35\text{A}$, $V_{GS} = 0$ to 10V	-	49	65	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 80\text{V}$, $I_D = 35\text{A}$	-	6.1	-	V

Reverse Diode

Inverse diode continuous forward current	I_S	$T_C = 25\text{ }^\circ\text{C}$	-	-	35	A
Inverse diode direct current, pulsed	I_{SM}		-	-	140	
Inverse diode forward voltage	V_{SD}	$V_{GS} = 0\text{V}$, $I_F = 35\text{A}$	-	0.95	1.25	V
Reverse recovery time	t_{rr}	$V_R = 50\text{V}$, $I_F = I_S$, $di/dt = 100\text{A}/\mu\text{s}$	-	80	100	ns
Reverse recovery charge	Q_{rr}		-	230	290	nC

1 Power dissipation

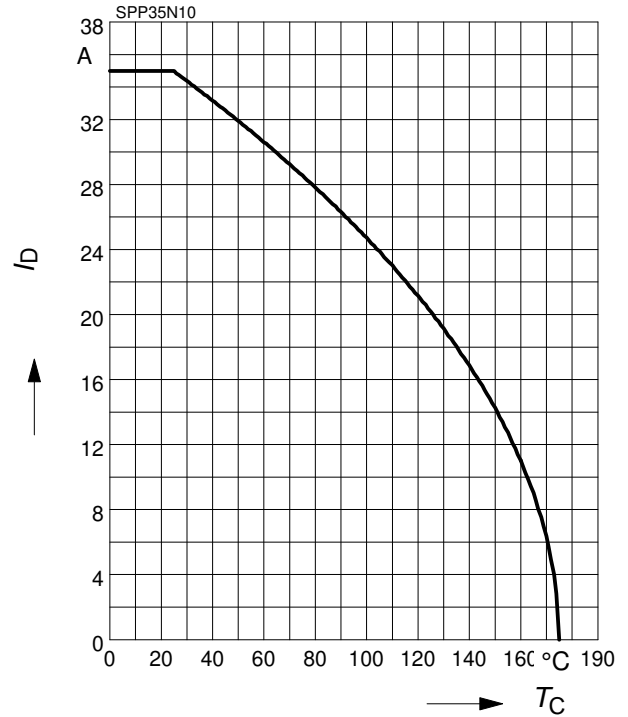
$$P_{tot} = f(T_C)$$



2 Drain current

$$I_D = f(T_C)$$

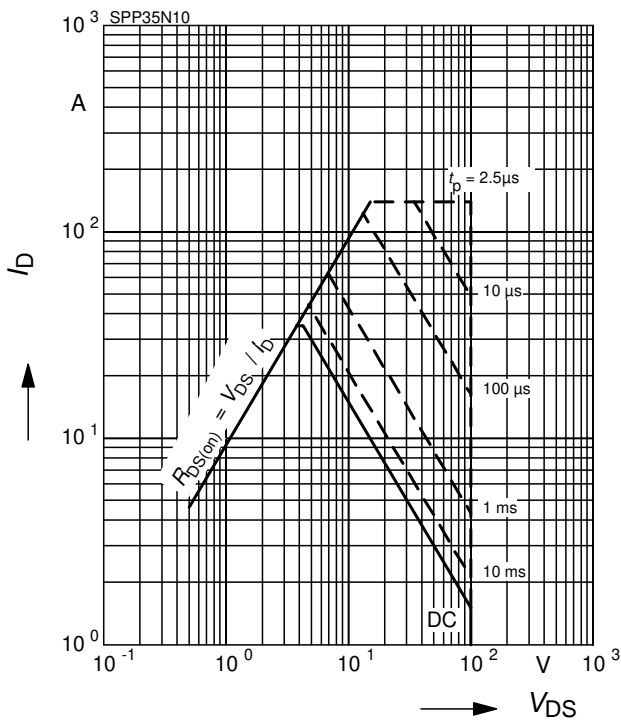
parameter: $V_{GS} \geq 10 \text{ V}$



3 Safe operating area

$$I_D = f(V_{DS})$$

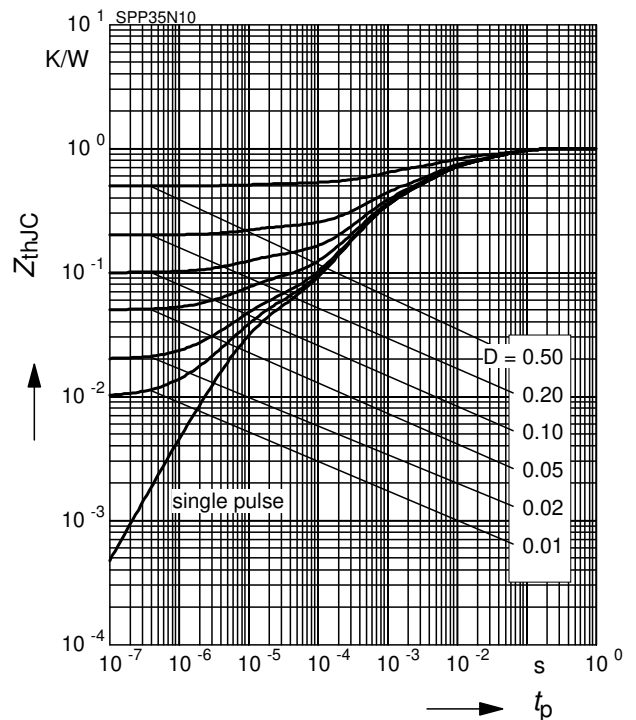
parameter: $D = 0$, $T_C = 25 \text{ °C}$



4 Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

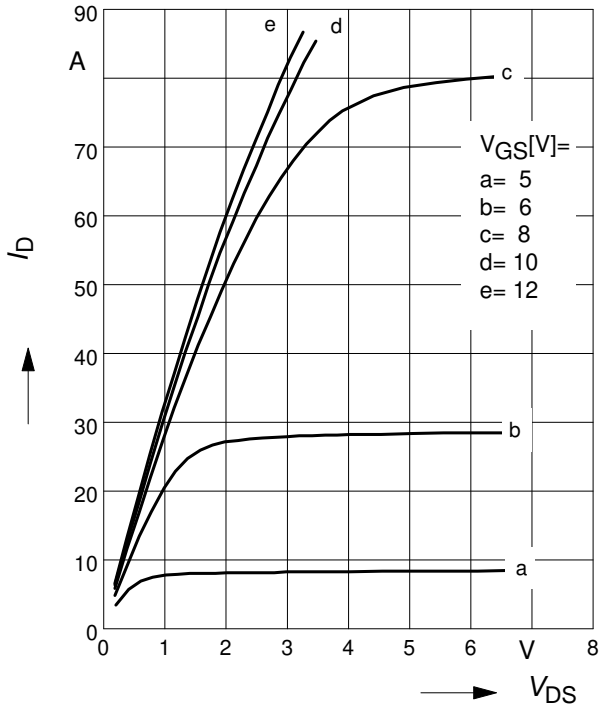
parameter: $D = t_p/T$



5 Typ. output characteristic

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

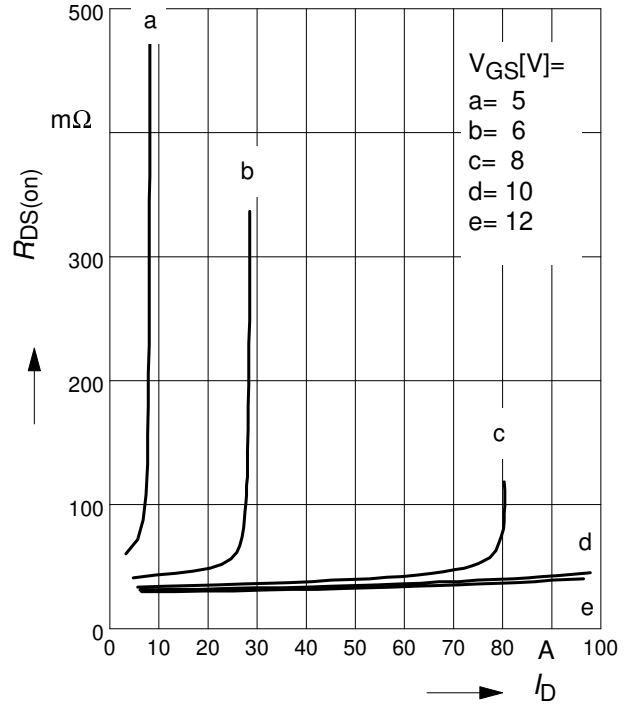
parameter: $t_p = 80 \mu\text{s}$



6 Typ. drain-source on resistance

$$R_{DS(on)} = f(I_D)$$

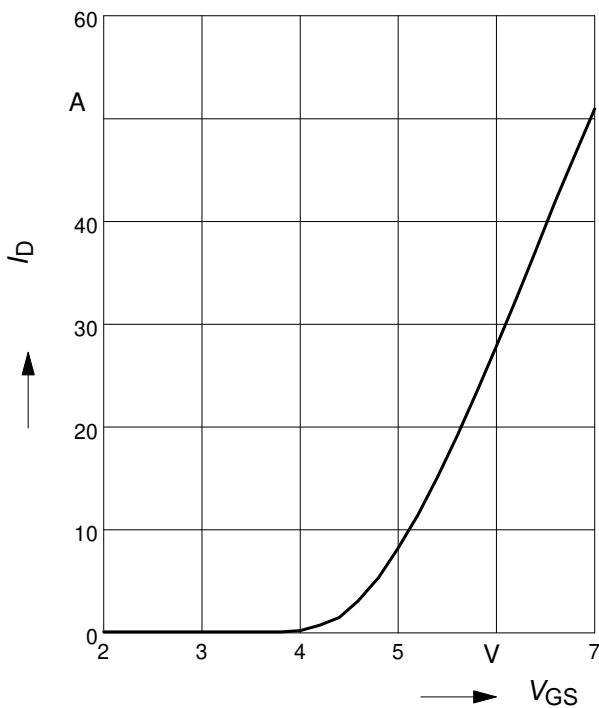
parameter: V_{GS}



7 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

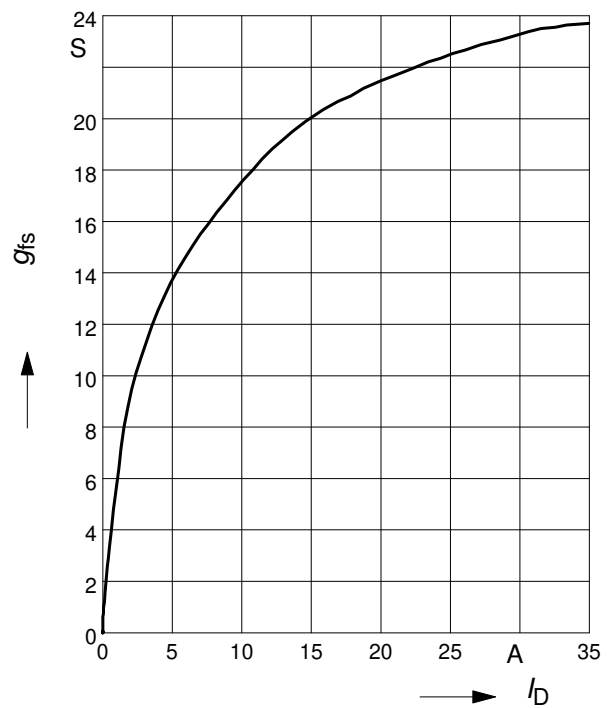
parameter: $t_p = 80 \mu\text{s}$



8 Typ. forward transconductance

$$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$$

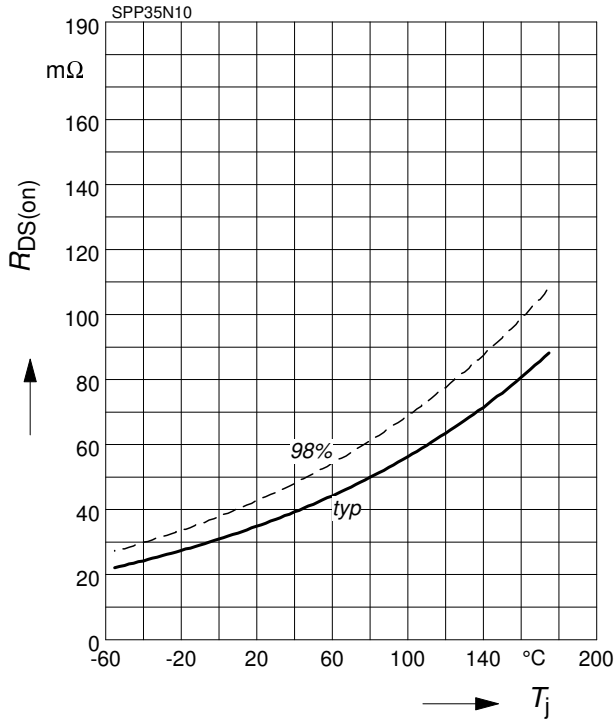
parameter: g_{fs}



9 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

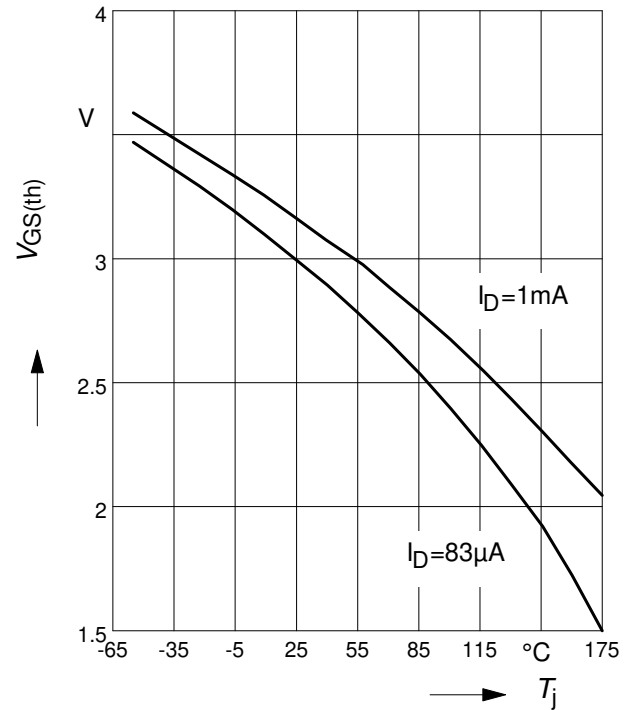
parameter : $I_D = 26.4 \text{ A}$, $V_{GS} = 10 \text{ V}$



10 Typ. gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

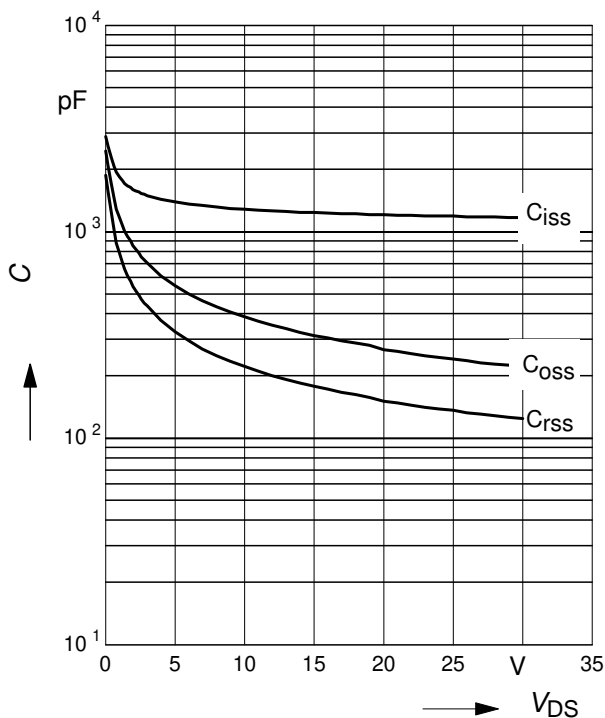
parameter: $V_{GS} = V_{DS}$



11 Typ. capacitances

$$C = f(V_{DS})$$

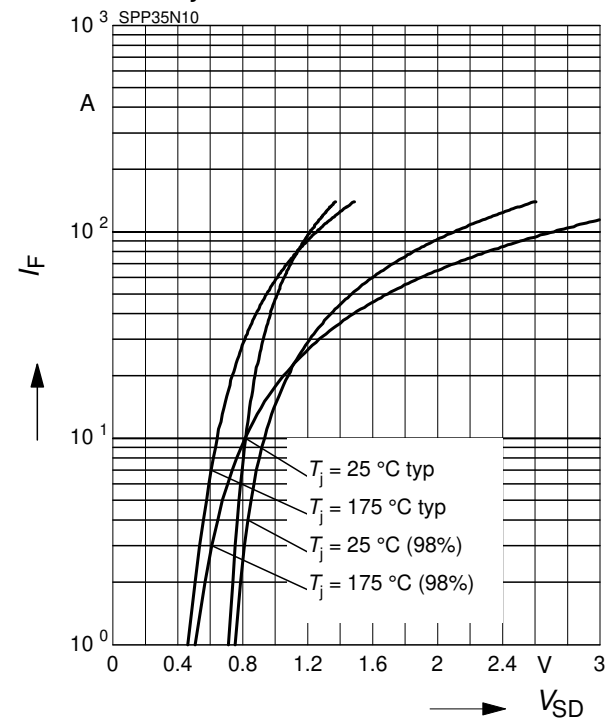
parameter: $V_{GS}=0\text{V}$, $f=1 \text{ MHz}$



12 Forward character. of reverse diode

$$I_F = f(V_{SD})$$

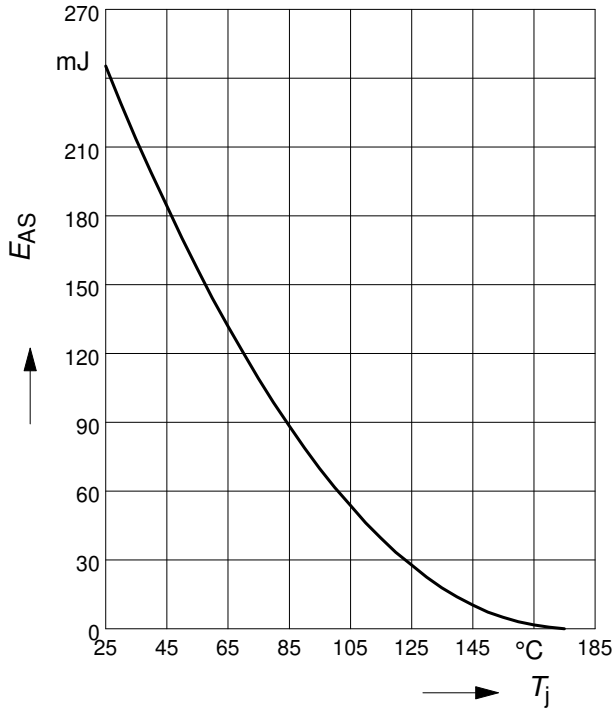
parameter: T_j , $t_p = 80 \mu\text{s}$



11 Typ. avalanche energy

$$E_{AS} = f(T_j)$$

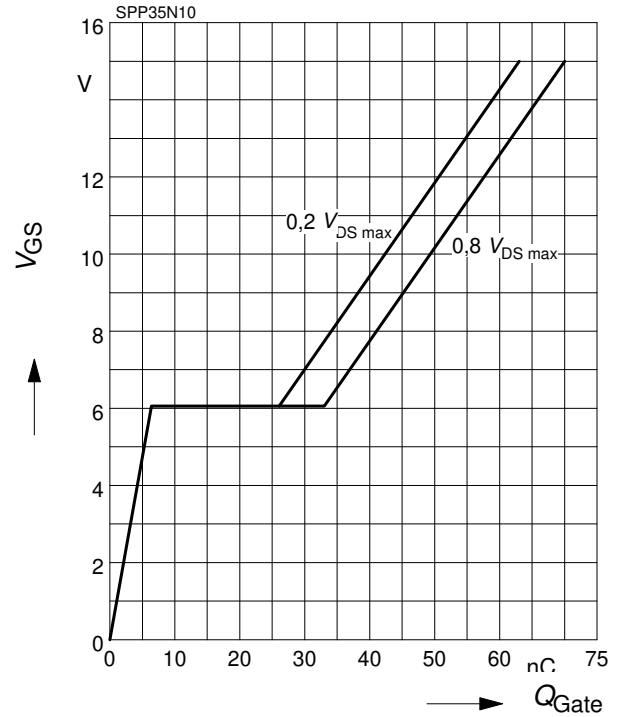
par.: $I_D = 35 \text{ A}$, $V_{DD} = 25 \text{ V}$, $R_{GS} = 25 \Omega$



12 Typ. gate charge

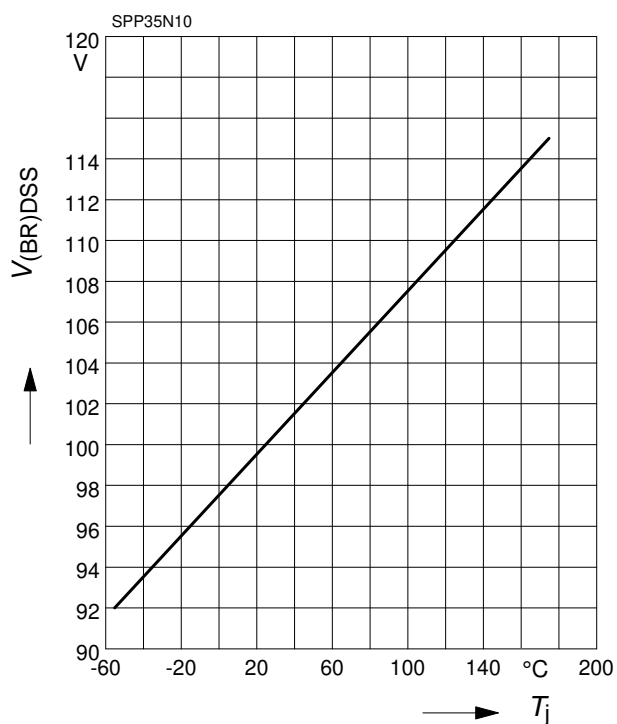
$$V_{GS} = f(Q_{Gate})$$

parameter: $I_D = 35 \text{ A}$ pulsed



13 Drain-source breakdown voltage

$$V_{(BR)DSS} = f(T_j)$$



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